Title (en)

Low profile interconnect structure

Title (de)

Verbindungsstruktur mit niedrigem Profil

Title (fr)

Structure d'interconnexion à profil bas

Publication

EP 1107655 A2 20010613 (EN)

Application

EP 00125898 A 20001127

Priority

US 45434299 A 19991203

Abstract (en)

Low profile interconnect structure includes an electronic circuit module with a plurality of mounting areas and a plurality of electrical contact areas defined by the mounting surface. The plurality of mounting areas are spaced a first distance from a mounting and interconnect surface parallel to and spaced from the mounting surface and the plurality of electrical contact areas are spaced a second distance, less than the first distance, from the mounting and interconnect surface. Large solder balls are used between the mounting areas and the mounting and interconnect surface to form a solid mount and smaller solder members are used for electrical interconnections. <IMAGE>

IPC 1-7

H05K 3/34

IPC 8 full level

H01L 21/60 (2006.01); **H01L 23/48** (2006.01); **H01L 23/498** (2006.01); **H05K 3/34** (2006.01)

CPC (source: EP KR US)

H01L 23/48 (2013.01 - KR); **H01L 23/49816** (2013.01 - EP US); **H01L 23/49838** (2013.01 - EP US); **H05K 3/3436** (2013.01 - EP US); H01L 2224/06102 (2013.01 - EP US); H01L 2224/14 (2013.01 - EP US); H05K 3/3463 (2013.01 - EP US); H05K 3/3485 (2020.08 - EP US); H05K 2201/094 (2013.01 - EP US); H05K 2201/09472 (2013.01 - EP US); H05K 2201/09781 (2013.01 - EP US); H05K 2203/041 (2013.01 - EP US); H05K 2203/0465 (2013.01 - EP US); Y02P 70/50 (2015.11 - EP US); Y10T 29/49142 (2015.01 - EP US); Y10T 29/49144 (2015.01 - EP US)

Cited by

CN110602363A

Designated contracting state (EPC)

AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)

EP 1107655 A2 20010613; **EP 1107655 A3 20020731**; CN 1223249 C 20051012; CN 1299230 A 20010613; JP 2001168131 A 20010622; JP 4545917 B2 20100915; KR 100719384 B1 20070517; KR 20010070229 A 20010725; US 6410861 B1 20020625

DOCDB simple family (application)

EP 00125898 A 20001127; CN 00134286 A 20001130; JP 2000360441 A 20001128; KR 20000069217 A 20001121; US 45434299 A 19991203